

Opening - The 21<sup>st</sup> Interfinish World Congress & Seminar (25 Nov,2024)  
2024年11月25日 - 第21届世界表面精饰大会暨研讨会开幕日

Tentative Schedule 暂定时间表 1<sup>st</sup> Day Diamond Hall

0830-0900	Registration 注册
0900-0930	Opening and Group Photo 开幕式及合照
0930-1000	Plenary Talk 1 by Ma Jie (CSEA) 会议演讲 1 – 马捷 (中国表面工程协会) Surface Engineering Technology 40 Years Of Progress In China 中国表面工程技术的 40 年发展
1000-1030	Plenary Talk 2 by Jimmy Kwok (HKSFS) 会议演讲 2 – 郭振华 (香港表面处理学会) A New Chapter For Materials Finishing In HK and Greater Bay Area
1030-1105	Break 休息, visiting program 導賞團 和 Booth visit 攤位參觀
1105-1150	Plenary Talk 3 by Prof K. Ryder (IMF UK) 会议演讲 3 – Prof Ryder (英国 IMF) Sustainable Manufacturing In The Finishing Industries And The Management Of Critical Technology Metals
1150-1315	Lunch time 午餐
1315-1400	Plenary Talk 4 by Prof S. Moon (Korean Society of Surface Science and Engineering) 会议演讲 4 – Prof Moon (韩国表面工程学会) Surface Finishing Technologies for Light Metals
1400-1445	Plenary Talk 5 by Dr. T. Gotstick (MacDermid Enthone) 会议演讲 5 – Dr. Gotstick (麦德美乐思) How Surface Finishing Can Contribute to A Cleaner World
1445-1530	Plenary Talk 6 by Prof Lawrence Li (City University of HK)会议演讲 6 – 李国恩教授(城大) Multilayer DLC For High-Contact Stress Applications
1530-1600	Break 休息, visiting program 導賞團 和 Booth visit 攤位參觀
1600-1645	Plenary Talk 7 by Prof Kanematsu (Suzuka College)/Prof Kure (Nagoya Institute of Technology) representing Surface Finishing Society of Japan 会议演讲 7 – 兼松秀行教授 (铃鹿工业高等专门学校)/吴松竹教授(名古屋工业大学)日本表面技术协会代表 Graphene & Graphene Oxide Dispersed Alkoxysilane Resin Coatings And Their Biofilm Properties
1645 - 1730	Plenary Talk 8 by Prof Sawada (Nagoya University Japan) 会议演讲 8 – 泽田康之教授(日本名古屋大学) Plasma Processing and Its Application to Materials for Energy Storage Devices
1730-1745	Closing Remarks 散会词
1900-2130	Conference Dinner and HKSFS 50 <sup>th</sup> Anniversary Dinner 晚宴

Day Two - The 21<sup>st</sup> Interfinish World Congress & Seminar (26 Nov, 2024)  
2024年11月26日 - 第21届世界表面精饰大会暨研讨会

Tentative Schedule 暂定时间表 2<sup>nd</sup> Day Plantinum Hall

0845-0900	Registration 注册
Advanced Materials Finishing	
0900-0940	Prof LI Ning (Harbin Institute of Technology) 李宁教授(哈工大) Preparation and Action Mechanism of Iridium-Coated Titanium Anode for Copper Plating of PCB With Low Additive Breakdown
0940-1020	Prof. ZHENG Zijian (Hong Kong Polytechnic University) 郑子剑教授(理大) Polymer-assisted Metal Deposition for Flexible Electronics
1020-1035	Break 休息
1035-1115	Prof. CHEN Yuanming (University of Electronic Science & Technology of China) 陈苑明教授(成都科大) Construction of Functional Metal Deposition Layer on Some Materials
1115-1155	Prof Shochiku Kure (Nagoya Institute of Technology) 吴松竹教授(名古屋工业大学) Tailored Fabrication of New Functional Composite Coatings on Various Non-Ferrous Metals Through Hybrid Surface Technologies for Next Generation Power Devices and High-Performance Batteries
1155-1320	Lunch time 午餐
1320-1400	Prof SUN Jian Jun (Fuzhou University) 孙建军教授(福州大学) Bump Electrodeposition Of Tin-Based Alloys For Advanced Packaging
Surface Finishing from Industrialization to Green Technology Development	
1400-1440	Prof FANG Jing Li (Nanjing University) 方景礼教授(南京大学) New Surface Finishing Technology For The Future III. Resource Recovery And Utilization Of Surface Finishing Wastewaters.
1440-1520	Prof. Sik Chol Kwon (Inha University – Graduate School of Engineer) Surface Technology, The Foundation of Korea's Industrial Development
1520-1535	Break 休息
1535-1615	Prof. Lin An (Wuhan University) 林安教授(武汉大学) Application Of Closed Cycle Technology In Electroplating Production Line In China
1615-1655	Nicholas Chang (HKSFS) 张志恒(香港表面处理学会) Surface Finishing From Industrialization To Green Technology Development
1655-1730	Closing Remarks 散会词

Day Two - The 21<sup>st</sup> Interfinish World Congress & Seminar (26 Nov, 2024)  
2024年11月26日 - 第21届世界表面精饰大会暨研讨会

Tentative Schedule 暂定时间表 2<sup>nd</sup> Day Gold Hall

0845-0900	Registration 注册
<b>Electronics Plating and Electroless Plating</b>	
0900-0940	Prof WEI Guoying (China Jiliang University) 卫国英教授(中国计量大学) Cobalt Alloy Electroplating And Application As Diffusion Barrier For Copper Interconnection
0940-1020	Prof. Tsunehisa Suzuki (Akita Prefectural University) 高桥辰宏教授(秋田县立大学) Nickel Deposition Mechanism Of Laser-Enhanced Electroless Plating Using CW Laser
1020-1035	Break 休息
1035-1115	Dr. Xiao Ning (Beijing University of Chemical Technology) 肖宁博士(北京化工大学) Synthesis And Performance Research Of Copper Plating Additives Used For PCB Microvia Filling
1115-1155	Prof FU Xian Zhu (Shenzhen University) 符显珠教授(深圳大学) Electroless Deposition Technology for Electrical Interconnections
1155-1320	Lunch time 午餐
<b>Industrial Applications of Surface Finishing</b>	
1320-1400	Prof. Yuttanant Boonyongmaneerat (Chulalongkorn University Thailand) Collaborative Research to Advance Nickel-Based Electrodeposition for High-Erosion and High-Temperature Applications
1400-1440	Prof. Jonathan Chung (City University of Hong Kong) 钟志源教授(香港城市大学) Good Practices In Mechanical Polishing Before More Precise Surface Finishing And Advanced Coating For Automotive And Watches Industries.
1440-1520	Mr. David Shi 史宏伟 (天津艾隆科技开发有限公司) The Development and Frontier of Aluminium Surface Treatment 铝表面处理的发展与前沿
1520-1535	Break 休息
1535-1615	赵永强 – 深圳市顺信精细化工有限公司 / 遂宁迪印科技有限公司 All-Solution-Processed Metallization of Through Glass Vias (TGVs) with a High Adhesion Promoting Layer (APL)
1615-1655	冯小龙 (宁波康强电子股份有限公司) Roll-to-Roll Continuous High-Precision Selective Photoresist Electroplating and Highly Reliable Brown Oxidation Technology
1655-1730	Closing Remarks 散会词 (Join in Platinum Hall)